



US00D778850S

(12) **United States Design Patent** (10) **Patent No.:** **US D778,850 S**  
**Matsumoto et al.** (45) **Date of Patent:** **\*\* Feb. 14, 2017**

(54) **SUBSTRATE FOR AN ELECTRONIC CIRCUIT**

(71) Applicant: **Kabushiki Kaisha Toshiba**, Minato-ku, Tokyo (JP)

(72) Inventors: **Manabu Matsumoto**, Yokohami (JP); **Isao Ozawa**, Chigasaki (JP)

(73) Assignee: **Kabushiki Kaisha Toshiba**, Minato-ku, Tokyo (JP)

(\*\*) Term: **15 Years**

(21) Appl. No.: **29/564,493**

(22) Filed: **May 13, 2016**

**Related U.S. Application Data**

(62) Division of application No. 29/500,896, filed on Aug. 29, 2014, now Pat. No. Des. 764,424.

(30) **Foreign Application Priority Data**

May 15, 2014 (JP) ..... 2014-010418  
May 15, 2014 (JP) ..... 2014-010419  
May 15, 2014 (JP) ..... 2014-010420  
May 15, 2014 (JP) ..... 2014-010421

(51) **LOC (10) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**  
USPC ..... D13/182, 123, 133, 110, 184, 199;  
257/177, 666, 684, 686, 689, 775;  
361/600, 601, 820; 29/825, 829, 830, 831,  
361/832; 174/68.1, 250, 253, 254, 260,  
2174/61, 268; 216/13; 428/901; D5/4, 61  
CPC ..... H01L 25/072; H01L 2224/48245;  
H01L 23/28; H01L 23/29; H01L 23/298;  
H01L 23/31; H01L 23/3107; H01L  
23/3121; H01L 23/3128; H01L 2924/14;  
C09K 19/00; C09K 19/02; G06F 1/183;  
G06F 1/184; G06F 1/187; G11B 33/12;  
G11B 33/123; G11B 33/124; G11B

33/125; G11B 33/127; G11B  
33/128; H05K 1/00; H05K 1/11; H05K  
1/111; H05K 1/112; H05K 3/0058; H05K  
3/0061; H05K 3/0064; H05K 3/0067  
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

D68,316 S 9/1925 Lader  
5,858,481 A 1/1999 Fukushima et al.  
6,410,355 B1\* 6/2002 Wallace ..... H01L 22/14  
257/107

(Continued)

FOREIGN PATENT DOCUMENTS

CN 488834 5/2002  
JP 104233 3/2001

(Continued)

*Primary Examiner* — Elizabeth J Oswecki

(74) *Attorney, Agent, or Firm* — Banner & Witcoff, Ltd.

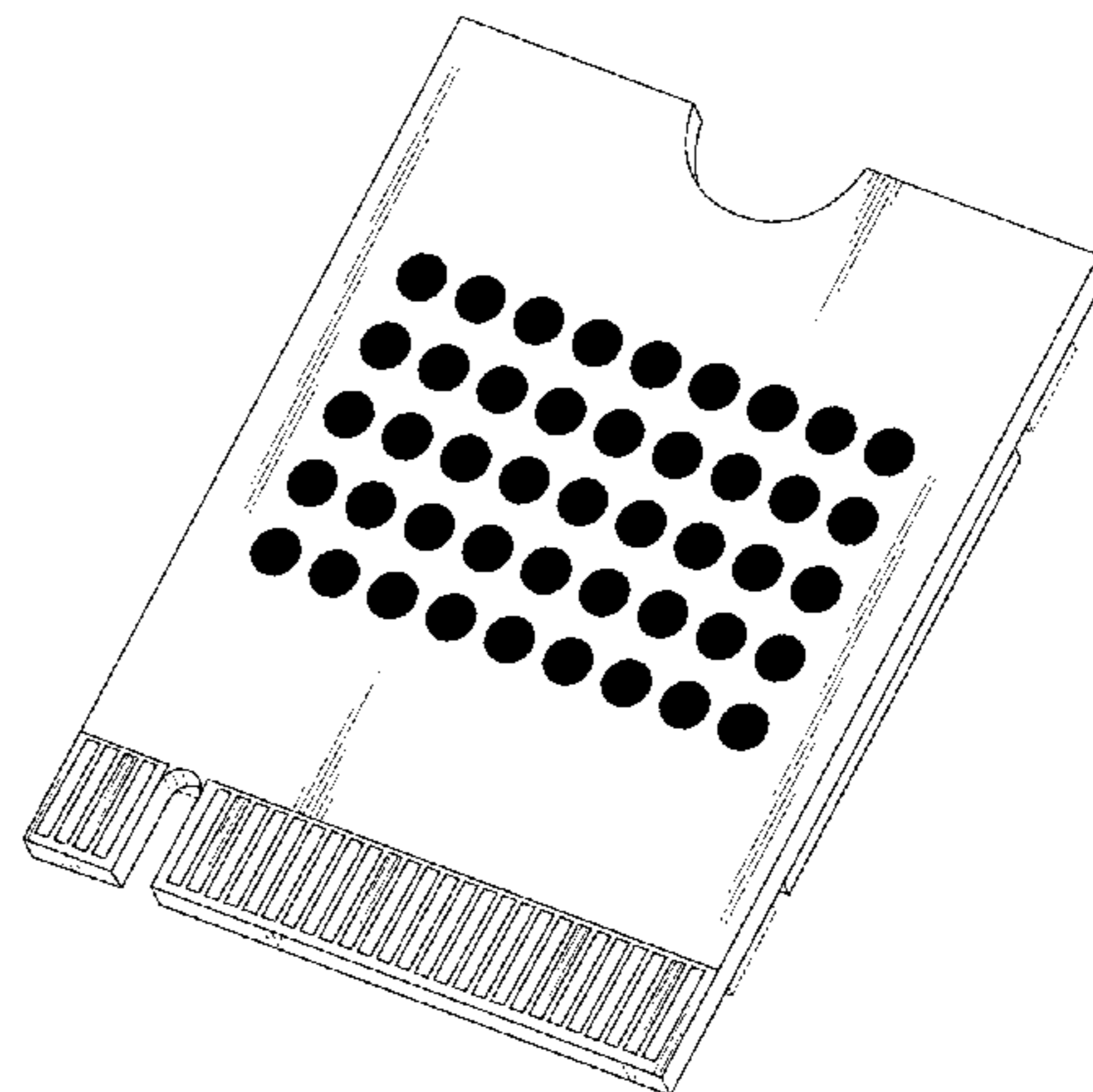
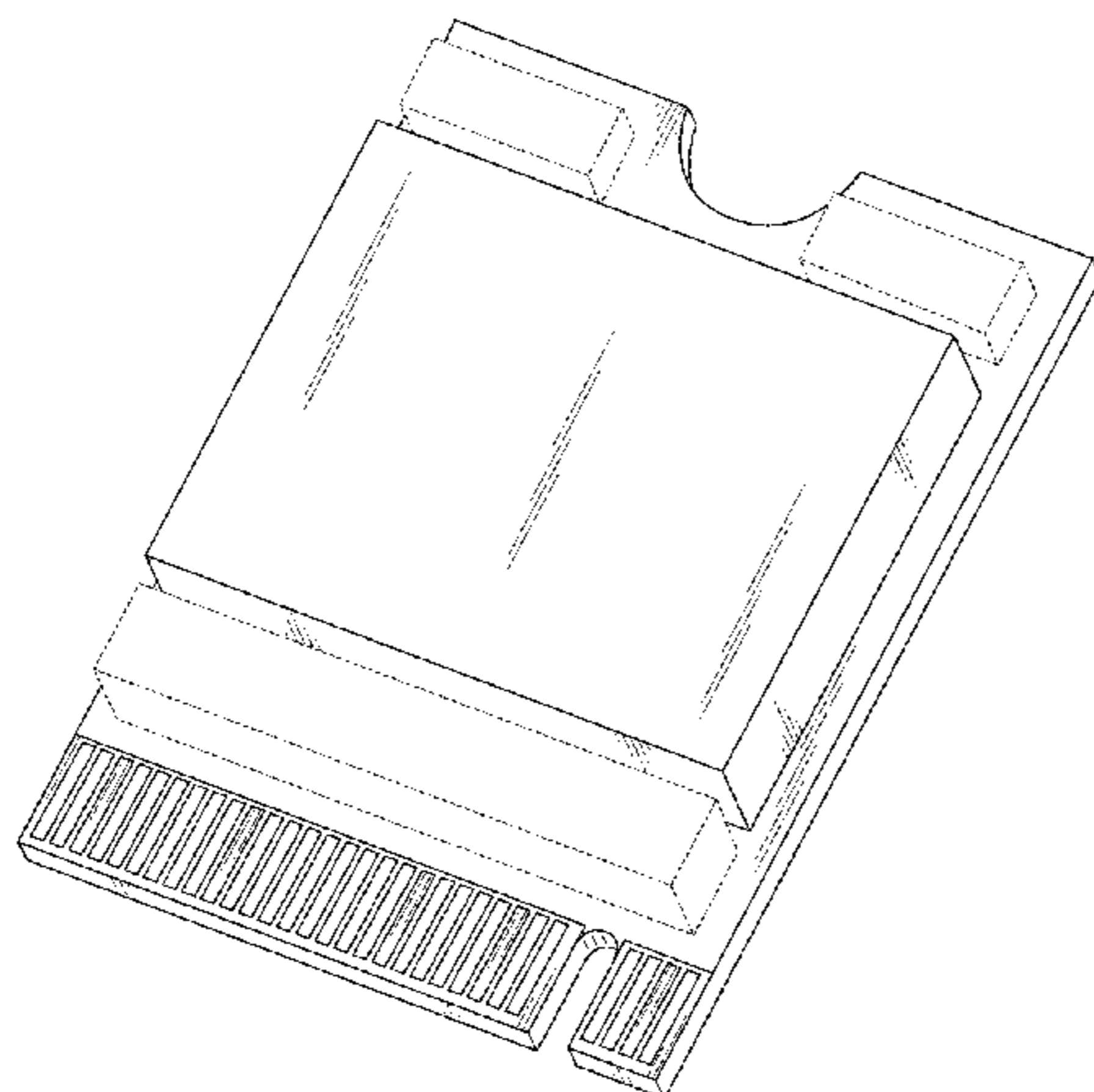
(57) **CLAIM**

The ornamental design for a substrate for an electronic circuit, as shown and described.

**DESCRIPTION**

FIG. 1 is a perspective view of a substrate for an electronic circuit showing our new design;  
FIG. 2 is a rear perspective view thereof;  
FIG. 3 is a front elevational view thereof;  
FIG. 4 is a rear elevational view thereof;  
FIG. 5 is a right side elevational view, a left side elevational view being a mirror image thereof;  
FIG. 6 is a top plan view thereof; and,  
FIG. 7 is a bottom plan view thereof.  
The broken lines shown in the drawings represent portions of the substrate for an electronic circuit that form no part of the claimed design.

**1 Claim, 5 Drawing Sheets**



(56)

References Cited

U.S. PATENT DOCUMENTS

D459,706 S 7/2002 Ebihara et al.  
 D471,524 S 3/2003 Ebihara et al.  
 D526,972 S 8/2006 Egawa et al.  
 D531,139 S 10/2006 Egawa et al.  
 7,306,161 B2\* 12/2007 Takiar ..... G06K 13/0825  
 235/441  
 7,307,848 B2\* 12/2007 Takiar ..... G06K 19/077  
 361/736  
 D608,741 S 1/2010 Miyashita  
 7,864,540 B2\* 1/2011 Takiar ..... G06K 19/04  
 361/736  
 D633,672 S 3/2011 McKnight  
 D633,673 S 3/2011 McKnight  
 D637,193 S 5/2011 Andre et al.  
 D670,917 S 11/2012 Blackford  
 D673,922 S 1/2013 Moriai et al.  
 D674,759 S 1/2013 Chang et al.  
 D686,175 S 7/2013 Gurary et al.  
 D686,582 S 7/2013 Krishnan et al.  
 D690,671 S 10/2013 Gurary et al.  
 D699,201 S 2/2014 Petsch

D702,445 S 4/2014 Boyle  
 D704,155 S 5/2014 Chang et al.  
 D716,743 S \* 11/2014 Hu ..... D13/182  
 D727,861 S \* 4/2015 Tang ..... D13/182  
 D730,304 S 5/2015 Matsumoto et al.  
 D753,073 S \* 4/2016 Sponring ..... D13/182  
 D757,666 S \* 5/2016 Yokoo ..... D13/182  
 D761,745 S \* 7/2016 Shinkai ..... D13/182  
 D764,424 S \* 8/2016 Matsumoto ..... D13/182  
 D768,115 S \* 10/2016 Kazanchian ..... D13/182  
 2003/0094628 A1 5/2003 Yeh et al.  
 2006/0168721 A1 8/2006 McGuire et al.  
 2008/0123318 A1 5/2008 Lam  
 2010/0326710 A1 12/2010 Zhang  
 2011/0051351 A1 3/2011 Harashima

FOREIGN PATENT DOCUMENTS

JP 1287854 12/2006  
 JP 1426168 10/2011  
 JP 1479369 9/2013  
 JP 1479370 9/2013  
 KR 30-0470075 11/2007

\* cited by examiner

Fig. 1

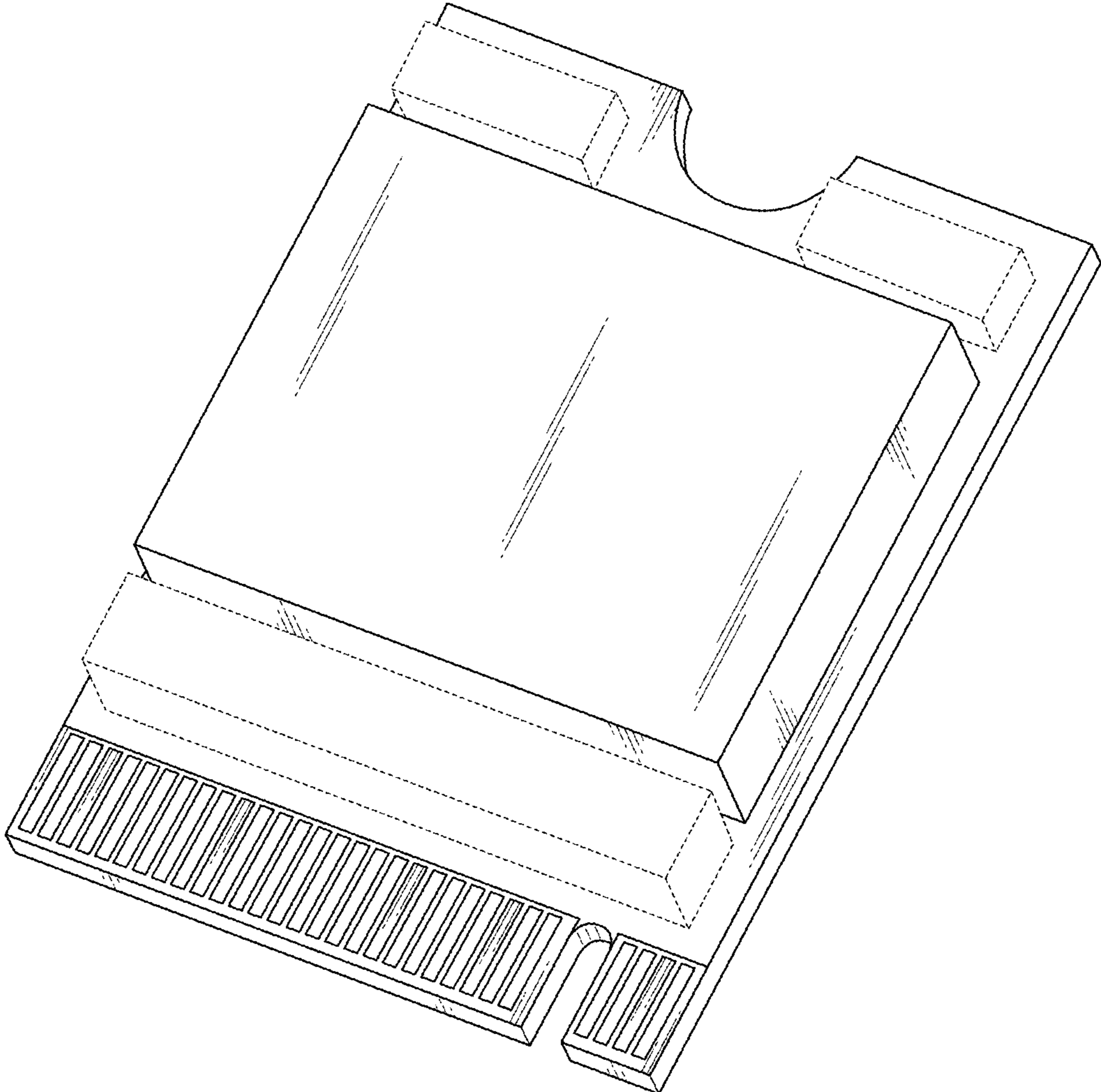


Fig. 2

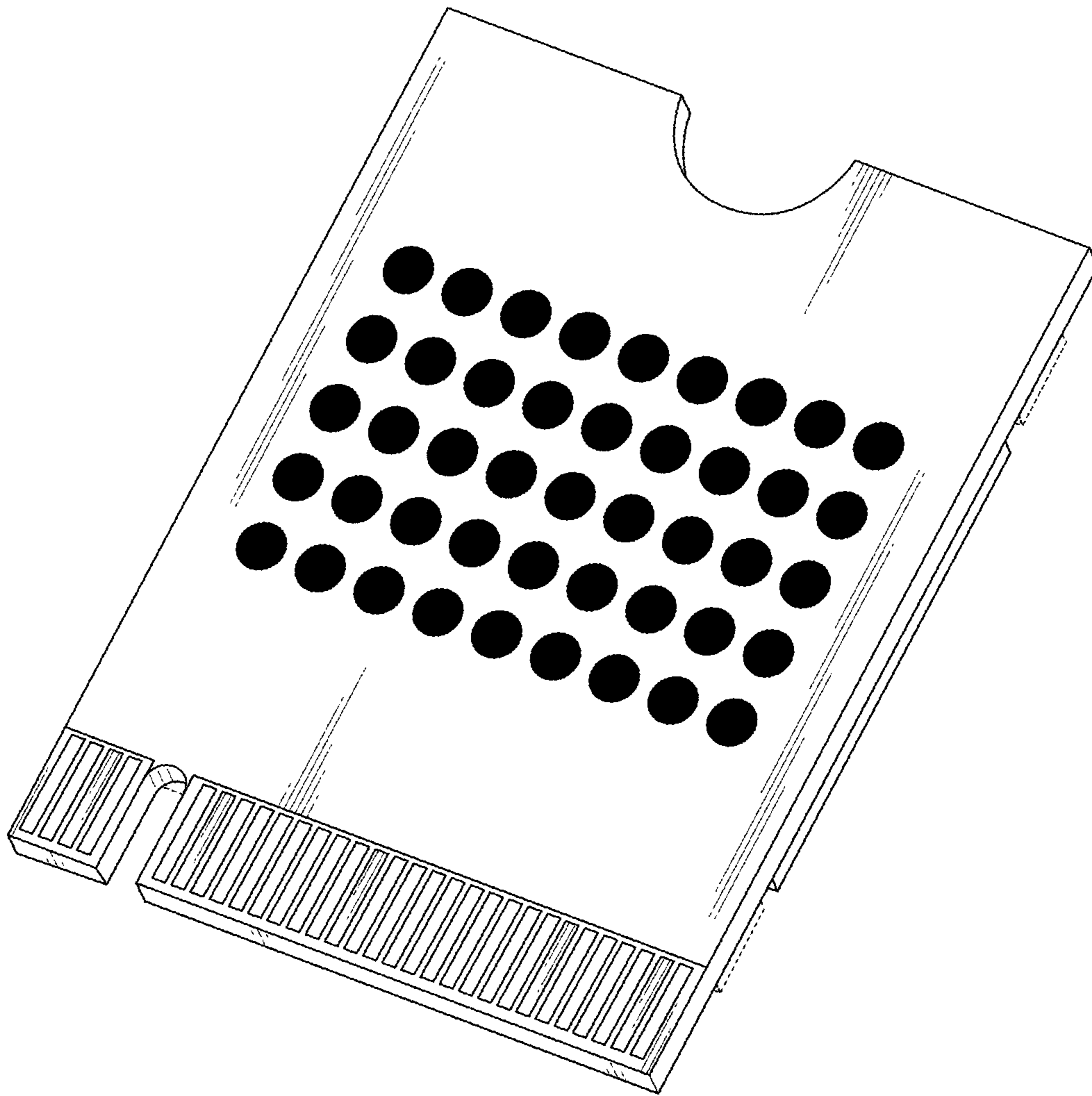




Fig. 3

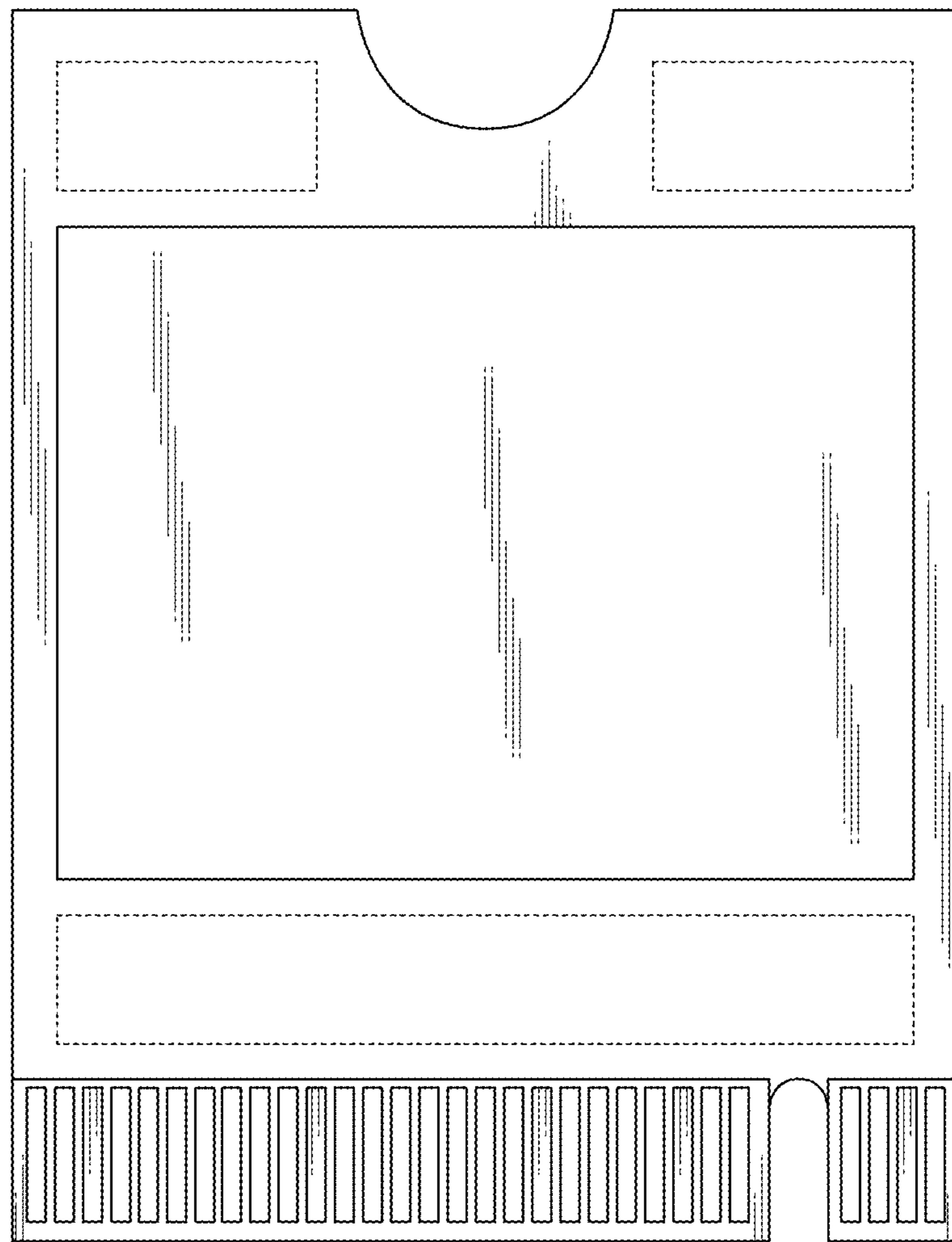


Fig. 4

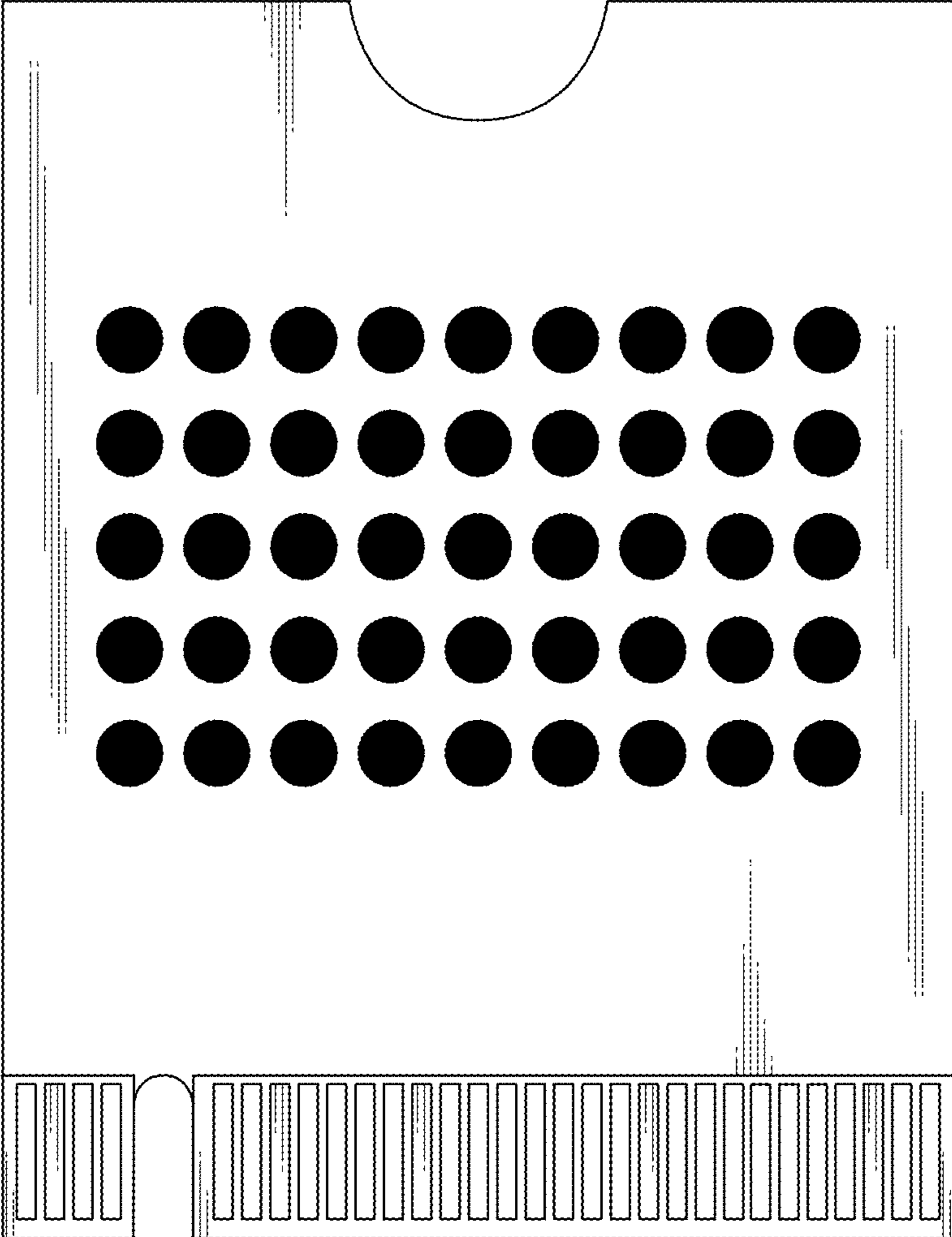


Fig. 5

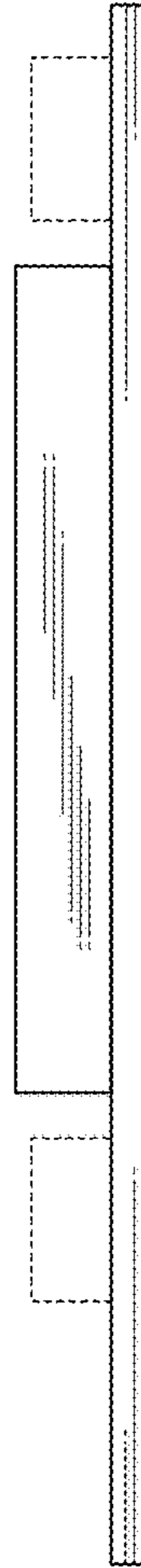


Fig. 6

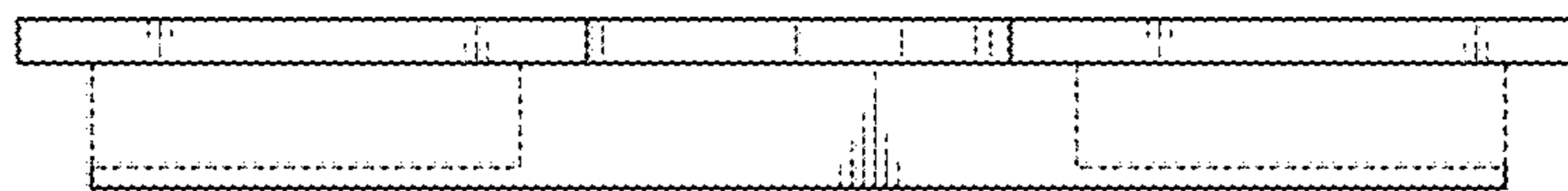


Fig. 7

